

## EAST Search History

| Ref # | Hits | Search Query                          | DBs   | Default Operator | Plurals | Time Stamp          |
|-------|------|---------------------------------------|---|------------------|---------|---------------------|
| S1    | 3855 | 250/370.01,370.08-370.14.ccls.        | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2009/04/02<br>10:38 |
| S2    | 4583 | 257/431,435,443,448.ccls.             | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2009/04/02<br>10:52 |
| S3    | 8340 | S1 S2                                 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2009/04/02<br>10:52 |
| S4    | 8    | (puhakka-kimmo   benson-lain).<br>in. | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2009/04/02<br>10:53 |

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| S5 | 8    | (puhakka-kimmo-\$   puhaka-kimmo   benson-lain).in.    | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>10:54 |
| S6 | 8    | (puhakka-kimmo-\$   puhaka-kimmo-\$   benson-lain).in. | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>10:54 |
| S7 | 5    | "556820".pn.   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>11:09 |
| S8 | 1    | 10/532119  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>11:24 |
| S9 | 3855 | 250/370.01,370.08-370.14.ccls.                         | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>13:44 |
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| S10 | 4583  | 257/431,435,443,448.ccls.                          | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>13:44 |
| S11 | 8340  | S9 S10   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>13:44 |
| S12 | 30427 | via with electrode with substrate                  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>13:45 |
| S13 | 10251 | (element pixel) with substrate<br>with (bump bond) | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>13:48 |
| S14 | 116   | S11 and S13  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>13:48 |

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| S15 | 921383 | (pixel detector array sensor)<br>with (circuit\$2 PCB board)                       | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>13:51 |
| S16 | 20784  | (pixel detector array sensor)<br>with (circuit\$2 PCB board) with<br>(bumps balls) | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>13:51 |
| S17 | 196    | S11 and S16  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>13:51 |
| S18 | 34     | S17 and (via hole) with<br>substrate with (through)                                | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>13:52 |
| S20 | 24     | S17 and (via hole) with<br>substrate near3 (through)                               | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>13:53 |

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| S21 | 17  | S17 and (via hole) with (pcb circuit\$2 board) near3 (through)                                    | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>13:54 |
| S22 | 18  | S17 and (via hole) with (electronics circuit\$2 process\$3) near (board substrate) with (through) | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>13:58 |
| S23 | 58  | S11 and (via hole) with (electronics circuit\$2 process\$3) near (board substrate) with (through) | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>13:58 |
| S24 | 235 | 250/370.13.ccls.  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>14:06 |
| S25 | 31  | (pixel detector array sensor) with (circuit\$2 PCB board) with (bumps balls) and S24              | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>14:06 |
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| S26 | 89   | chen-henry.in.  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>14:12 |
| S27 | 9374 | solder adj mask   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>14:12 |
| S28 | 3    | S26 and S27   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>14:12 |
| S29 | 56   | ("20010035497"  <br>"20020066531"  <br>"20020182716"  <br>"20030173523"  <br>"20070158574"   "5100767"  <br>"5368882"   "5677539"  <br>"5905264"   "5933706"  <br>"6034373"   "6037595"  <br>"6043106"   "6046068"  <br>"6069360"   "6121622"  <br>"6175120"   "6215123"  <br>"6329658"   "6333504"  <br>"6333504"   "6410922"  <br>"6510195"   "6524966"  <br>"6694172"   "6765213"  <br>"6765213"   "6781132"  <br>"7038288"   "7223981").PN. | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>14:13 |

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| S30 | 37   | (pixel detector array sensor) with (circuit\$2 PCB board read \$1out chip) with (bumps balls) and S24 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>14:18 |
| S32 | 1433 | (circuit\$2 wiring board PCB PWB read\$1out) with (via holes) and S11                                 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>14:20 |
| S33 | 350  | (read\$1out) with (via holes) and S11   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>14:21 |
| S34 | 53   | (read\$1out) with (via holes) with (board substrate) and S11  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>14:21 |
| S35 | 24   | (read\$1out) with (via holes) near3 (board substrate) and S11   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>14:22 |

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| S36 | 29  | (read\$1out) with (via holes channel) near3 (board substrate) and S11             | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>14:35 |
| S37 | 505 | (readout read\$1out) with (via holes channel) and S11                             | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:04 |
| S38 | 107 | (readout read\$1out) with (via holes channel) with through and S11                | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:04 |
| S39 | 18  | (readout read\$1out) with (via holes channel) with through with substrate and S11 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:05 |
| S40 | 15  | S24 AND read\$1out with vias  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:08 |



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| S41 | 0  | S24 AND read\$1out with through near substrate   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:09 |
| S42 | 0  | S24 AND read\$1out with through near3 substrate  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:09 |
| S43 | 8  | S24 AND read\$1out with hole   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:10 |
| S44 | 59 | S11 and read\$1out with substrate with (hole via through near2 substrate)                  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:11 |
| S45 | 48 | S11 and read\$1out with substrate with (conduct\$3 near2 hole via through near2 substrate) | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:12 |

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| S46 | 1  | S11 and read\$1out with mount<br>with (conduct\$3 near2 hole via<br>through near2 substrate)                                     | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:16 |
| S47 | 5  | S11 and read\$1out with mount<br>\$3 with (conduct\$3 near2 hole<br>via through near2 substrate)                                 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:16 |
| S48 | 3  | 250/338.1-353.ccls. and read<br>\$1out with mount\$3 with<br>(conduct\$3 near2 hole via<br>through near2 substrate)              | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:18 |
| S49 | 42 | 250/338.1-353.ccls. and (circuit<br>\$2 read\$1out) with mount\$3<br>with (conduct\$3 near2 hole via<br>through near2 substrate) | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:19 |
| S50 | 45 | S11 and (circuit\$2 read\$1out)<br>with mount\$3 with (conduct\$3<br>near2 hole via through near2<br>substrate)                  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:19 |

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| S51 | 8  | S11 and tile with (array detector pixel) with substrate with read \$1out      | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>15:24 |
| S52 | 1  | read\$1out adj (circuit\$2 board) with mount and S11                          | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>17:35 |
| S53 | 20 | read\$1out adj (circuit\$2 board) with mount\$3 and S11                       | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>17:36 |
| S54 | 22 | read\$1out adj (circuit\$2 board) with (housing mount\$3) and S11             | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>17:36 |
| S55 | 42 | read\$1out adj (circuit\$2 board) with (support\$3 housing mount \$3) and S11 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>17:36 |

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| S56 | 59  | read\$1out adj (circuit\$2 board with (support\$3 housing carrier mount\$3) and S11 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>17:37 |
| S57 | 478 | read\$1out adj (circuit\$2 substrate board) and S11                                 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>17:45 |
| S58 | 18  | S57 and flip\$1chip   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>17:45 |
| S59 | 11  | read\$1out with (securing mount \$3) with support\$3 and S11                        | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>17:48 |
| S60 | 13  | read\$1out with (securing mount \$3) with (mount support\$3) with via               | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>17:52 |

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| S61 | 0    | read\$1out with (securing mount \$3) with (mount support\$3) with conduct\$3 adj (opening hole pathway) | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>17:54 |
| S62 | 338  | read\$1out with (securing mount \$3 support\$3) with (opening hole pathway)                             | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>18:06 |
| S63 | 7    | S62 and S11   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/02<br>18:07 |
| S64 | 112  | read\$1out WITH mount\$3 WITH (printed adj (circuit wiring adj board) PCB PWB)                          | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>10:32 |
| S65 | 3865 | 250/370.01,370.08-370.14.ccls.  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>10:32 |

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| S66 | 4585 | 257/431,435,443,448.ccls.  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>10:32 |
| S67 | 8352 | S65 S66  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>10:32 |
| S68 | 21   | S64 and S67  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>10:33 |
| S69 | 4    | (US-20080093560-\$ or US-20030155516-\$).did. or (US-5962909-\$ or US-6403964-\$).<br>did. | US-PGPUB;<br>USPAT  | OR | ON | 2009/04/07<br>14:05 |
| S70 | 4    | S69 and via  | US-PGPUB;<br>USPAT  | OR | ON | 2009/04/07<br>14:06 |
| S71 | 3865 | 250/370.01,370.08-370.14.ccls.   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:14 |

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| S72 | 4585  | 257/431,435,443,448.ccls.  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:14 |
| S73 | 8352  | S71 S72  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:14 |
| S74 | 18223 | "257".clas. and via adj (passage hole channel)   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:15 |
| S75 | 277   | "257".clas. and via adj (passage hole channel) same ((insulat\$3 shield\$3) with ground) | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:16 |
| S76 | 3     | S73 and via adj (passage hole channel) same ((insulat\$3 shield\$3) with ground)         | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:16 |

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| S77 | 525 | via adj (passage hole channel) with ((insulat\$3 shield\$3) with ground)                     | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:17 |
| S79 | 181 | "257".clas. and via adj (passage hole channel) with ((insulat\$3 shield\$3) with ground)     | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:18 |
| S80 | 93  | "257".clas. and via with substrate with ((insulat\$3 shield\$3) with ground) with conductive | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:53 |
| S81 | 0   | "257".clas. and via with substrate with insulat\$3 with ground with conductive adj shield\$3 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:54 |
| S82 | 2   | "257".clas. and via with substrate same insulat\$3 with ground same conductive adj shield\$3 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:54 |



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| S83 | 2  | "257".clas. and via same insulat<br>\$3 with ground same conductive<br>adj shield\$3                                | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:54 |
| S84 | 41 | "257".clas. and via and insulat<br>\$3 with ground and conductive<br>adj shield\$3                                  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:55 |
| S85 | 9  | "257".clas. and via adj (hole<br>channel passage) and insulat\$3<br>with ground and conductive adj<br>shield\$3     | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:55 |
| S86 | 11 | via adj (hole channel passage)<br>and insulat\$3 adj (layer film)<br>with ground and conductive adj<br>shield\$3    | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:58 |
| S87 | 12 | via adj (hole channel passage)<br>and insulat\$3 adj (layer film)<br>with ground\$2 and conductive<br>adj shield\$3 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>14:58 |

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| S88 | 0   | via adj (hole channel passage)<br>with insulat\$3 adj (layer film)<br>with ground\$2 and conductive<br>adj shield\$3 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>15:02 |
| S89 | 123 | via with insulat\$3 adj (layer<br>film) and conductive adj shield<br>\$3   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>15:02 |
| S90 | 25  | via with insulat\$3 adj (layer<br>film) same conductive adj shield<br>\$3  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>15:03 |
| S92 | 66  | via near3 conductive adj shield<br>\$3   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>15:03 |
| S94 | 55  | S92 and insulat\$3   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>15:04 |

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| S95  | 24  | via with substrate with<br>conductive adj shield\$3  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>15:05 |
| S96  | 5   | (US-20080093560-\$ or US-<br>20030155516-\$).did. or (US-<br>5962909-\$ or US-6403964-\$ or<br>US-6952042-\$).did. | US-PGPUB;<br>USPAT  | OR | ON | 2009/04/07<br>15:28 |
| S97  | 625 | conductive adj shield\$3 with<br>potential   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>15:28 |
| S100 | 2   | conductive adj shield\$3 with<br>potential and S96   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>15:29 |
| S101 | 56  | faraday adj shield\$3 with via   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>15:30 |
| S102 | 2   | faraday adj shield\$3 with via<br>with substrate   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/07<br>15:51 |

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| S103 | 2    | "20020130266".pn.                                 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/08<br>10:09 |
| S104 | 3865 | 250/370.01,370.08-370.14.ccls.                    | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/08<br>14:18 |
| S105 | 4585 | 257/431,435,443,448.ccls.                         | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/08<br>14:18 |
| S106 | 8352 | S104 S105   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/08<br>14:18 |
| S107 | 1128 | S106 and (photo\$1lithograph\$2<br>lithograph\$2) | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/08<br>14:19 |

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| S108 | 68 | S106 and (photo\$1lithograph\$2 lithograph\$2) with via              | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/08<br>14:19 |
| S109 | 11 | S106 and (photo\$1lithograph\$2 lithograph\$2) with via adj hole     | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/08<br>14:19 |
| S110 | 8  | S109 and photo\$1resist\$3   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/08<br>14:20 |
| S111 | 36 | S108 and photo\$1resist\$3   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/08<br>14:24 |
| S112 | 27 | S106 and (photo\$1lithograph\$2 lithograph\$2) with etch\$3 with via | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/08<br>14:33 |

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| S113 | 7    | S106 and (photo\$1lithograph\$2 lithograph\$2) with etch\$3 with via with substrate          | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/08<br>14:33 |
| S114 | 1    | S106 and (photo\$1lithograph\$2 lithograph\$2) same etch\$3 with via adj hole with substrate | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/08<br>14:48 |
| S115 | 5    | S106 and etch\$3 with via adj hole with substrate  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/08<br>14:48 |
| S116 | 3865 | 250/370.01,370.08-370.14.ccls.   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>09:23 |
| S117 | 4586 | 257/431,435,443,448.ccls.  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>09:23 |

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| S118 | 8353 | S116 S117  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>09:23 |
| S119 | 5    | method with etch\$3 with via adj<br>hole and S118  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>09:24 |
| S120 | 1755 | method with etch\$3 with via adj<br>hole and "257".clas.   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>09:26 |
| S121 | 21   | method with etch\$3 with via adj<br>hole with substrate same (photo<br>\$1lithograph\$2 lithograph\$2)<br>and (photo\$1resist\$3) and<br>"257".clas.               | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>09:27 |
| S122 | 2    | method with etch\$3 with via adj<br>hole with substrate same (photo<br>\$1lithograph\$2 lithograph\$2)<br>same (photo\$1resist\$3) same<br>mask\$3 and "257".clas. | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>09:31 |

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| S123 | 8  | method with etch\$3 with via adj<br>hole with substrate same (photo<br>\$1lithograph\$2 lithograph\$2)<br>same (photo\$1resist\$3) same<br>mask\$3 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>09:36 |
| S124 | 87 | method with etch\$3 with via adj<br>hole with substrate same (photo<br>\$1resist\$3) same mask\$3  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>09:37 |
| S125 | 61 | S124 and "257".clas.   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>09:37 |
| S126 | 8  | S116 and photo\$1resist\$3 with<br>(adher\$3 adhesive)   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>11:05 |
| S127 | 15 | S116 and (adher\$3 adhesive)<br>with (detector substrate) with<br>read\$1out   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>11:22 |



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| S128 | 15 | S116 and (adher\$3 adhesive) with (detector substrate) with (flip\$1chip read\$1out)  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>11:28 |
| S129 | 21 | S116 and (adher\$3 adhesive) with (detector substrate) with (flip\$1chip electronic\$2 read \$1out)   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>11:29 |
| S130 | 11 | S116 and (adher\$3 adhesive) with (anode electrode) with (epoxy photo\$1resist\$3 mask \$3)   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>11:33 |
| S131 | 56 | ("20010035497"  <br>"20020066531"  <br>"20020182716"  <br>"20030173523"  <br>"20070158574"   "5100767"  <br>"5368882"   "5677539"  <br>"5905264"   "5933706"  <br>"6034373"   "6037595"  <br>"6043106"   "6046068"  <br>"6069360"   "6121622"  <br>"6175120"   "6215123"  <br>"6329658"   "6333504"  <br>"6333504"   "6410922"  <br>"6510195"   "6524966"  <br>"6694172"   "6765213"  <br>"6765213"   "6781132"  <br>"7038288"   "7223981").PN. | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>11:35 |

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| S132 | 0     | S131 and (adher\$3 adhesive) with (anode electrode)                        | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>11:36 |
| S133 | 8     | S131 and (adher\$3 adhesive)   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>11:36 |
| S134 | 14120 | fill\$3 with (electrode anode) with contact                                | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>11:39 |
| S135 | 21    | fill\$3 with (electrode anode) with contact and S116                       | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>11:39 |
| S136 | 0     | S116 and (adher\$3 adhesive) with (anode electrode) with photo\$1resist\$3 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>12:00 |

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| S137 | 0 | S116 and (adher\$3 adhesive)<br>with read\$1out with photo<br>\$1resist\$3 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>12:00 |
| S138 | 5 | S116 and (adher\$3 adhesive)<br>with substrate with photo\$1resist<br>\$3  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>12:00 |
| S139 | 1 | S116 and (adher\$3 adhesive)<br>with epoxy near3 photo\$1resist<br>\$3     | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>12:01 |
| S140 | 3 | S116 and (adher\$3 adhesive)<br>with epoxy with photo\$1resist\$3          | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>12:02 |
| S141 | 3 | S118 and (adher\$3 adhesive)<br>with epoxy with photo\$1resist\$3          | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>12:02 |

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| S142 | 15 | S118 and (adher\$3 adhesive)<br>with photo\$1resist\$3                           | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>12:03 |
| S143 | 34 | thickness near3 substrate with<br>via adj (hole channel passage)<br>with thin\$4 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/04/09<br>12:33 |

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